attaching at least one active face-down base die to said substrate in electrical communication with at least some of said conductors;

securing the back side of at least one active face-up stack die to said base die; [and]

electrically connecting said stack die to at least one of said conductors;

securing at least one discrete component to at least one of said stack die, said base die, and said substrate; and

electrically connecting said at least one discrete component to at least one of said stack die, said base die, and said substrate.

21. (Amended) The method of claim 19, further comprising:

[securing at least one discrete component to said base die; and]

extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

22. (Amended) The method of claim 19, further comprising:

[securing at least one discrete component to said base die; and]

extending a component-to-substrate bond wire between said at least one discrete component and [a] at least one of said plurality of substrate [conductor] conductors.

23. (Amended) The method of claim 19, further comprising:

securing a second stack die to said assembly; and

electrically connecting said second stack die and at least one of said plurality of substrate [conductor] conductors.

26. (Amended) The method of claim 25, further comprising:

securing at least one discrete component to said stack die; and

extending a die-to-component bond wire between said second stack die and said at least one discrete component.

27. (Amended) The method of claim [26] 25, further comprising:
securing at least one discrete component to said stack die; and
extending a component-to-substrate bond wire between said at least one discrete component and [a] at least one of said plurality of substrate [conductor] conductors.

28. (Amended) The method of claim 25, further comprising:
securing at least one discrete component to said base die; and
extending a die-to-component bond wire between said second stack die and said at least one discrete component.

29. (Amended) The method of claim 25, further comprising:
securing at least one discrete component to said base die; and
extending a component-to-substrate bond wire between said at least one discrete component and [a] at least one of said plurality of substrate [conductor] conductors.

30. (Amended) The method of claim 19, further comprising attaching a second active face-down base die to said substrate in electrical communication with at least one of said plurality of substrate conductors.

33. (Amended) The method of claim 19, further comprising:
securing at least one discrete component to said substrate; and
extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

34. (Amended) The method of claim 31, further comprising:
securing at least one discrete component to said substrate; and
extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.